## Medium Voltage High Capacitance for General Use Specifications and Test Methods

No.	. Item		Specifications	Test Method			
1	Operating Temperatu	re Range	-55 to +125°C -				
2	Appearan	се	No defects or abnormalities	Visual inspection			
3	Dimensio	ns	Within the specified dimensions	Using calipers and micrometers			
4	Dielectric	Strength	No defects or abnormalities	No failure should be observed when 150% of the rated volta (200% of the rated voltage in case of rated voltage: DC250/ 120% of the rated voltage in case of rated voltage: DC1kV) applied between the terminations for 1 to 5 sec., provided th charge/discharge current is less than 50mA.			
5	Insulation R (I.R.)	Resistance	C≧0.01μF: More than 100MΩ • μF C<0.01μF: More than 10,000MΩ	The insulation resistance should be measured with DC500±50V (DC250±25V in case of rated voltage: DC250V) and within 60±5 sec. of charging.			
6	Capacitar	nce	Within the specified tolerance	The experimental E should be measured at a fragment of			
7	Dissipation Factor (D.F.)		0.025 max.	<ul> <li>The capacitance/D.F. should be measured at a frequency of 1±0.2kHz and a voltage of AC1±0.2V(r.m.s.)</li> </ul>			
8				The capacitance measurement should be made at each step specified in the Table.			
				Step Temperature (°C)			
	Conseitor		Can Change	1         25±2           2         Min. Operating Temp.±3			
	Capacitar Temperat		Cap. Change Within ±15%	2         Min. Operating Temp.±3           3         25±2			
	Characteristics		(Temp. Range: –55 to +125°C)	4 Max. Operating Temp.±2			
				5 25±2			
				•Pretreatment Perform a heat treatment at 150 <sup>+0</sup> <sub>10</sub> °C for 60±5 min. and then let sit for 24±2 hrs. at room condition.*			
9	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 1. Then apply 10N force in the direction of the arrow. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. $\begin{array}{c} \hline \\ \hline $			
		Appearance	No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board). The capacitor should be subjected to a simple harmonic motion			
10		Capacitance	Within the specified tolerance				
	Vibration Resistance	D.F.	0.025 max.	having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each of 3 mutually perpendicular directions (total of 6 hrs.).			

\* "Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa

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۱o.	Ite	Item Specifications						Test Method		
			No marking defe	ects				Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2.		
1	Deflection	ı	→ → → → → → → → → → → → → → → → → → →					Then apply a force in the direction shown in Fig. 3. The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock. $20^{50}$ Pressurizing pressurize Pressurize		
			L×W			ion (mm)				
			(mm)	а	b	c	d		Flexu	ire=1
			1.6×0.8 2.0×1.25	1.0 1.2	3.0	1.2 1.65	-		Capacitance meter	
			3.2×1.6	2.2	5.0	2.0	10		45 45	(in mm)
			3.2×2.5	2.2	5.0	2.9	1.0		Fig. 3	
			4.5×3.2	3.5	7.0	3.7	-			
			<u>5.7×5.0</u>	4.5	8.0	5.6				
12	Solderabi Terminati		75% of the terminations are to be soldered evenly and continuously.					Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in solder solution for 2±0.5 sec. Immersing speed: 25±2.5mm/s Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu) 235±5°C H60A or H63A Eutectic Solder		
		Appearance	No marking defe	ects				Preheat the capacitor at 120 to 150°C* for 1 min. Immerse the capacitor in solder solution at 260±5°C for 10±1		
		Capacitance								
		Change	Within ±10%					sec. Let sit at room condition* for 24±2 hrs., then measure. •Immersing speed: 25±2.5mm/s		
	Resistance to Soldering Heat	D.F.	0.025 max.					•Pretreatment		
12			C>0.01uE: Mor	a than 100	MO • uE			Perform a heat treatment at 150 <sup>±</sup> <sub>1</sub> %°C for 60±5 min. and then		
13		I.R.	C≧0.01μF: More than 100MΩ • μF C<0.01μF: More than 10,000MΩ					let sit for 24±2 hrs. at room condition.*		
		Dielectric Strength	In accordance with item No.4					*Preheating f	or more than 3.2×2.5mm	
								Step	Temperature	Time
		Suengui						1 2	100 to 120°C 170 to 200°C	1 min. 1 min.
		Appearance							tor to the supporting jig (glas	
								in Fig. 4.		
		Capacitance Change						Perform the 5 cycles according to the 4 heat treatments listed in		
		D.F.	0.025 max.					the following table. Let sit for $24\pm 2$ hrs. at room condition,* then measure.		
		D.F.								Time (min.)
		I.R.	C≥0.01µF: Mor					Step 1	Temperature (°C) Min. Operating Temp.±3	30±3
			C<0.01µF: More		00010122			- 2	Room Temp.	2 to 3
								3	Max. Operating Temp.±2	30±3
4	Temperature							4	Room Temp.	2 to 3
14	Cycle	Dielectric Strength						Pretreatment		
								Perform a heat treatment at $150^{+}_{-1}$ $^{0\circ}_{-0}$ C for $60\pm5$ min. and ther let sit for 24 $\pm2$ hrs. at room condition.*		
			In accordance v	In accordance with item No.4						
									<u> ₹</u> Sol	der resist
									Cu	
								Glass Epoxy Board Fig. 4		
15	Humidity (Steady State)	Appearance	No marking defects							
		Capacitance Change	Within ±15%					Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500±24 hrs. Remove and let sit for 24±2 hrs. at room condition,* then measure. •Pretreatment Perform a heat treatment at 150±1% C for 60±5 min. and then		
		D.F.	0.05 max.							
		I.R.	С≥0.01µF: More than 10MΩ • µF C<0.01µF: More than 1,000MΩ							
				e than 1,00	JOIVISS				sat treatment at $150-10$ C it	

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No.	Item		Specifications	Test Method		
16	Life	Appearance	No marking defects	Apply 120% of the rated voltage (150% of the rated voltage in case of rated voltage: DC250V, 110% of the rated voltage in case of rated voltage: DC1kV) for $1,000^{\pm48}$ hrs. at maximum operating temperature $\pm3^{\circ}$ C. Remove and let sit for 24±2hrs. at room condition,* then measure.		
		Capacitance Change	Within $\pm 15\%$ (rated voltage: DC250V, DC630V) Within $\pm 20\%$ (rated voltage: DC1kV)			
		D.F.	0.05 max.			
		I.R.	C≧0.01μF: More than 10MΩ ∙ μF C<0.01μF: More than 1,000MΩ	he charge/discharge current is less than 50mA. •Pretreatment		
		Dielectric Strength	In accordance with item No.4	Apply test voltage for 60±5 min. at test temperature. Remove and let sit for 24±2 hrs. at room condition.*		
	Humidity Loading (Application: DC250V, DC630V item)	Appearance	No marking defects			
		Capacitance Change	Within ±15%	Apply the rated voltage at $40\pm2^{\circ}$ C and relative humidity of 90 to 95% for $500\pm^{23}$ hrs.		
17		D.F.	0.05 max.	Remove and let sit for 24±2 hrs. at room condition,* then measure.		
		I.R.	C≥0.01µF: More than $10M\Omega \bullet \mu F$ C<0.01µF: More than 1,000MΩ	•Pretreatment Apply test voltage for 60±5 min. at test temperature.		
		Dielectric Strength	In accordance with item No.4	Remove and let sit for 24±2 hrs. at room condition.*		

Continued from the preceding page.

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